



IPC-6903A

Terms and Definitions for the Design and Manufacture of Printed Electronics

Developed by the D-64a Printed Electronics Terms and Definitions
Task Group of the D-64 Printed Electronics Final Assembly
Subcommittee of IPC

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Users of this publication are encouraged to participate in the
development of future revisions.

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Any document involving a complex technology draws material from a vast number of sources. While the principal members of the of IPC are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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Terms and Definitions for the Design and Manufacture of Printed Electronics

1 SCOPE

This standard provides industry-approved terms and definitions for the design and manufacture of printed electronics.

1.1 Purpose The purpose of this standard is to provide the electronics industry with terms and definitions for specifying, designing and manufacturing printed electronics (additive processes).

The reader is encouraged to also reference IPC-2291, IPC-4591, IPC-6901 and IPC-9204, which have additional industry-approved terms and definitions.

1.2 Precedence Terms and definitions in this standard will be submitted to working groups in the IPC Printed Electronics Committee and the IPC Terms and Definitions Committee for inclusion in IPC-T-50 and other IPC standards for printed electronics. The definition of terms in those standards **shall** take precedence over those published in this standard. For ease of use, some terms from IPC-T-50 have been included in this standard and are marked with an asterisk (*).

1.3 Revision and Submitting New Terms This standard **shall** undergo revision or amendments in instances in which:

- A term(s) is presented to the D-64a Task Group and that term does not fit the scope or need of another standard
- A revision or amendment of this standard can be approved faster than the standard for which the term(s) was developed.

2 APPLICABLE DOCUMENTS

2.1 IPC¹

IPC-T-50 Terms and Definitions for Interconnecting and Packaging Electronics Circuits

IPC-2291 Design Guideline for Printed Electronics

IPC-4591 Requirements for Printed Electronics Functional Conductive Materials

IPC-6901 Application Categories for Printed Electronics

IPC-9204 Guideline on Flexibility and Stretchability Testing for Printed Electronics

3 TERMS AND DEFINITIONS FOR PRINTED ELECTRONICS

Aerosol Printing Printing technology that deposits material in a form of high-speed mist stream of microdroplets, capable of producing high-resolution in patterns on planar and nonplanar substrates.

Aggregates A collection of particles joined together which cannot be broken down.

Alignment (Registration) Use of an outer-positioning camera or sensor to move a substrate to the correct position manually or in automated form.

Anilox A cylinder with etched or engraved wells.

Annealing, Metals A treatment that alters the microstructure of a material, causing changes in properties such as strength and hardness, to induce ductility and relieve internal stresses.

Annealing, Plastics A treatment that alters the microstructure of a material causing changes in properties to improve strength and hardness, to reduce internal stresses related to the polymer structure.

Annealing, Printed Functional Material A treatment that can be used to enhance electrical performance (i.e., reduce electrical resistance) of a printed functional material.

Arc Plasma Heating Arc heating utilizing disposable graphite electrodes which generate an arc plasma between the material and electrode, thus transferring the energy to the material. Arc plasma heating captures the arc plasma with a nozzle or gas flow. It can offer higher orientation and higher temperature than normal arc heating.

Area Gain Area in the actual feature contour outside the nominal feature contour.

Area Loss Nonprinted area of a nominal feature.

1. www.ipc.org